

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SW WANG	07/20/2017
HOW KIAT LIEW	07/20/2017
CH CHEW	07/20/2017
EIJI KUROSE	07/18/2017
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<b>Name:</b>	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
<b>Street Address:</b>	5005 E. MCDOWELL ROAD
<b>Internal Address:</b>	MAILDROP A700
<b>City:</b>	PHOENIX
<b>State/Country:</b>	ARIZONA
<b>Postal Code:</b>	85008
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15679666
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<b>ATTORNEY DOCKET NUMBER:</b>	ONS02434US
<b>NAME OF SUBMITTER:</b>	SHARRON CASTILLO
<b>SIGNATURE:</b>	/Sharron Castillo/
<b>DATE SIGNED:</b>	08/17/2017
<b>Total Attachments: 3</b>	

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## ASSIGNMENT & AGREEMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

Name	of (City and State OR Country)
Sw WANG	Seremban Malaysia
CH CHEW	Seremban Malaysia
Eiji KUROSE	Ora-gun, Oizumi-machi Japan
How Kiat LIEW	Bukit Jalil Malaysia

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

**Title: MOLDED SEMICONDUCTOR PACKAGE AND RELATED METHODS**

**Attorney Docket No.: ONS02434US**

**Serial No.: 15/679666**

**Filing Date: August 17, 2017**

together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

We further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

We agree that, when requested, we will, without charge to SCI, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing, maintaining, and enforcing the Patent Rights in any and all countries and for vesting title thereto in SCI or its nominees.

We represent and warrant that we have full right to convey the entire right, title and interest herein sold, assigned, and transferred, and that the Patent Rights hereby conveyed are free from all prior assignment, grant, mortgage, license, or other encumbrance to anyone other than SCI. We covenant and further warrant that we will not convey hereafter any part of the Patent Rights to anyone other than SCI or do any act whatsoever conflicting with this ASSIGNMENT & AGREEMENT.

We hereby authorize SCI or anyone it may properly designate to insert in this ASSIGNMENT & AGREEMENT the filing date and serial number of the above listed application(s) when ascertained. More than one counterpart of this ASSIGNMENT & AGREEMENT may be executed, each of which will be deemed an original.

By (Inventor signature): Wang  
Sw WANG

Witnessed by (Witness signature): [Signature]

Printed name of Witness: Liong Jin Yoong

Signed and Witnessed on (date): 20 Jul 2017

By (Inventor signature): [Signature]  
How Kiat LIEW

Witnessed by (Witness signature): [Signature]

Printed name of Witness: Liong Jin Yoong

Signed and Witnessed on (date): 20 JUL 2017

By (Inventor signature): [Signature]  
CH CHEW

Witnessed by (Witness signature): [Signature]

Printed name of Witness: Liong Jin Yoong

Signed and Witnessed on (date): 20 JUL 2017

ASSIGNMENT & AGREEMENT

ONS02434US

By (Inventor signature): Eiji Kurose  
Eiji KUROSE

Witnessed by (Witness signature): Takeshi Noma

Printed name of Witness: Takeshi Noma

Signed and Witnessed on (date): July 18, 2017